Build Up HDI (Standard)

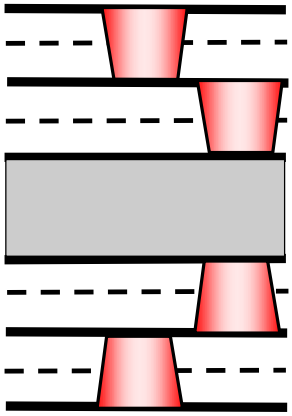
HDI06_2+2+2_1,60_35_engl

6 - Layers

Core: 1,20 mm Cu 35/35 µm

WE-Articel No.:	**2 + 2 + 2**
Customer:	

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	**60**	
	2		Foil	12 µm		**30**	
					1 x 1080	**60**	
	3			35 µm		**33**	
			1,200 mm			**1200**	
	4			35 µm		**33**	
					1 x 1080	**60**	
	5		Foil	12 µm		**30**	
					1 x 1080	**60**	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1590

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**1,60**	+/-	0,13	mm			Date:	Engineer:
thickness with electro plated Cu:	1,69	+/-	0,16	mm				
total thickness with soldermask	1,75	+/-	0,18	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision	
05.01.2006	**S. Keller**	04.05.2006	M.Kress	05.01.2006	R. Schönholz	00	page: 9+